

Design of Beetle1.3

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Motivation for Beetle1.3

in descending order of priority:

- Sticky Charge Effect
- Comparator Offset Variation
- 80 MHz Cross Talk
- Output Driver Performance
- Sagging Readout Baseline







Sticky Charge Effect (1)

- signal carry–over from previous event into an empty event, strong baseline drift
- only present for consecutive readouts, i.e. during a readout operation a further trigger arives



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Sticky Charge Effect (3): Simulations



Modification in Beetle1.3: analog delay of MuxTrack by 5 ns -





Sticky Charge Effect (4)

probe needle test with pos. and neg. phase shift





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Comparator Changes

Motivation: offset–spread: σ = 2.4 DAC units = 300 nA = 0.2 MIP

- bipolar
- too large for compensation with present DACs for channel threshold

Measures:

- merging input buffers: reduces additional offset
- gain increase of buffer: reduces influence on offset
- increase resolution of threshold current to 5 bits required: ±900 nA = ±0.6 MIP







80 MHz X-talk

cross talk with a frequency	spectrum of 8	80 MHz
present on digital signals, e.g. Data analogue signals, e.g. Ar power supply lines: Vddo	/alid nalogOut I, Vdda	
comparison:	Beetle1.1	Beetle1.2
# flip-flops:	1349	3043
# clock buffers:	21	284
guard rings logic core:	analogue	digital



Possible solutions: reduced no. of clock buffers on-chip power blocking







Readout Baseline Variation







Modifications in Beetle 1.3

Design Changes (on schematic level)

analogue delay of MuxTrack	signal fix of sticky charge effect
improved comparator	5 bit channel threshold resolutior
Current Output Buffer	increased gain, diff. output current
Mux: Switch Control	reduction of switching spikes
Control Logic	bug fixes (daisy chain op., low-Rclk op.)
new I2C–Pads	5V compatible
modified test pulse pattern	"+1/-1" patterr

X-talk Measures

- reduced no. of FF in multiplexer
 by factor 3 (414 -> 138)
- reduced no. of clock buffers in logic core
- on-chip power blocking

275 -> 104



Modifications in Beetle 1.3

Layout and Power Routing Issues

- modified front–end power pads (power and ground at top and bottom of chip)
- improved shaper power routing
- improved front-end biasing scheme
- separation of comparator core and LVDS pad power
- improved pipeamp power routing
- separation of power supply of multiplexer and logic core
- introduction of bias generator probe pad
- implementation of 2 new power pads for logic core (located at bottom side)
- merged pad openings of adjacent power pads
- on-chip power blocking
 in total 1375 gate caps: ~ 0.9 nF
- improved guard ring structures n-well and substrate contacts

This all together increased chip size by 300 um in x-direction (now: 5400 x 6100 um2)



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LHCh **Testpulse / Front-end**

Testpulse

- reduced testpulse pattern (+1 / -1)
- improved guardring structure





readout channels

		esistances	Beetle 1.2 [mOhm/ch.]	Beetle 1.3 [mOhm/ch.]
Front-end	power:	Rpreamp	13.83	12.37
• revised power routing (esp. Shaper)		Rshaper1	39.21	11.17
		Rshaper2	70.24	
 decoupling capacitors in Buffer (1.3pF/cl 		Rbuffer	137.70	39.69
 modified bias schema improved guardring structure 	bias:	Rprebias	478.64	151.78
		Rprebias1	690.40	278.26
		Rshabias	1569.02	492.94
		Rshabias1	650.30	201.31
		Rbufbias	1569.02	985.88



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Front-end simulation

- Testpulse, Front-end and Pipeline
- 128 channels
- with channel to channel resitors













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Kick Power Supply / Pads



- chip length increased from 5100µm to 5400µm
- new arrangement of analog power pads
- additional power pads for digital core
- separation of power comparator core / LVDS output driver
- RoTokenIn and RoReTokenIn with int. pulldown
- merged adjacent digital power pads
- I2C pads SCL / SDA now 5V tolerant
- power separation of digital core and multiplexer
- power separation of analog part (MUX/pipeamp) and current output driver
- improved ESD protection
- on chip decoupling capacitors





On-Chip Blocking Capacitors





Fix of Sticky Charge Effect





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Control Logic: Functional Changes

- bug fix: daisy chain token handling last chip in daisy chain (DaisyLast) is no longer sensitive to return token signal (RoReTokenIn)
- bug fix: operation with Rclk < 0.5 Sclk
 - **Beetle1.2:** multiple generation of 'ReleaseColumn' signal (depending on Rclk/Sclk ratio) results in FIFO overflow
 - **Beetle1.3:** generation of 'ReleaseColumn' signal is independent of Rclk frequency
- equalising control sequence cons. / non-consec. readout





Control Logic: Clock Routing

Topology: clock trunk



layout view of FastControl

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Control Logic: Power Routing

- merged pad openings of existing power pads: enables 1–2 additional bond wires per pad
- additional power pads at bottom side
- blocking capacitors: 414 (core) + 96 (pads): 1/3 nF
- reduced area of FastControl (– 80 um in y–direction): allows improved power routing







Beetle 1.3

- submitted June 2003
- expect to be back: September 2003



